

NO PATTERN AREA  
 NO CIRCUIT AREA  
 SOLDER AREA

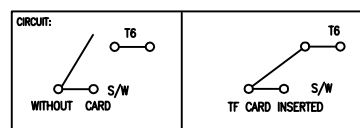
P.C.B LAYOUT  
(TOLERANCE±0.05)

TF CARD PIN ASSIGNMENT

PIN NO.	PIN ASSIGNMENT
T1	DAT2
T2	CD/DAT3 <sup>2</sup>
T3	CMD
T4	VDD
T5	CLK
T6	VSS
T7	DAT0
T8	DAT1

SIM pin assignment

	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved



NOTE:

- 一.材质及电镀方式 (MATERIAL AND FINISH)
- 1.塑胶 (HOUSING):LCP, UL 94V-0, COLOR:WHITE
  - 2.端子 (CONTACT):COPPER ALLOY  
GOLD FLASH PLATING ON CONTACT AREA,  
GOLD FLASH PLATING ON SOLDER TAILS  
50u" NICKEL UNDER PLATING OVER ALL
  - 3.铁壳 (SHELL):SUS304-3/4H  
40u" NICKEL UNDER PLATING OVER ALL

二.机械特性 (MECHANICAL CHARACTERISTICS)

- 1.唇? 薯? Insertion Force):2.0Kgf Max
- 2.拔出力 (Withdrawal Force):0.1Kgf Min
- 3.耐久性 (Durability):5000次

三.电气特性

- 1.额定电流 (Current rating):1.0A AC/DC
- 2.接触电阻 (Contact resistance):100mΩ MAX
- 3.绝缘电阻 (Insulation resistance):500MΩ MIN
- 4.适用温度 (Operating temperature):-20℃ ~65℃



深圳市华宇创精密电子有限公司

<b>TOLERANCE:</b> XX ±0.30 XXX ±0.25 XXXX ±0.15 X* ±2° X.X* ±0.5°	<b>DRAWN BY:</b> 陈一鸣	<b>DATE:</b> 2014-02-23	<b>PART NAME:</b> MICRO SIM+TF 同向2IN1卡座 两脚DIP
	<b>CHECKED BY:</b> 马跃	<b>DATE:</b> 2014-02-23	<b>PART NO.:</b> HYCW43-2IN117-183B
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	<b>APPROVED BY:</b> 邱敏	<b>DATE:</b> 2014-02-23	<b>DRAW NO.:</b> HVC-1811223711
			<b>SHEET NO.:</b> 1 OF 1